

Amendments to the Specification:

Please replace the paragraph beginning at page 12, line 26 with the following amended paragraph:

To keep connection areas 20a, 20b from being pushed away from the upper inside wall of the injection mold 200 during the procedure according to the invention, an injection mold 200 for a component housing according to the invention (cf. Fig. 5b) is shaped so that in the closed state, with connector strips 2a, 2b clamped inside, it also abuts, with an inner face, the surfaces of connector strips 2a, 2b opposite connection areas 20a, 20b.

Connector strips 2a, 2b are thereby pressed, in a region of connection areas 20a, 20b, against sections 201a and 201b of the appurtenant inner wall of the injection mold in such fashion that they are sealed off. Such an injection mold 200 for producing an inventive component housing therefore greatly reduces the risk that connection areas 20a, 20b will become covered with injection compound during the transfer molding of a housing base body.

Please replace the Abstract on page 17 with the following amended paragraph:

Abstract

~~Leadframe-based component housing, leadframe ribbon, surface-mountable electronic component and method of production~~

~~The invention describes a~~ A leadframe-based housing for a surface-mountable component, particularly a radiation-emitting component. ~~Said~~ The leadframe-based housing comprises electrical connector strips and at least one chip mounting area. ~~area,~~ and ~~provided according to the invention in one~~ One of the connector strips ~~is~~ includes an

injection aperture that enables a leadframe-based housing to be produced with a very small thickness in an injection molding process. A method for producing such housings is further specified.

Figure 4b